

Amendments to the Claims:

Applicants propose to cancel claims 16-32, 34-39, and 42-49, and amend claims 14-15 as follows:

14. (Twice Amended) A method for stopping polishing of a substrate at a desired endpoint, comprising:

monitoring a characteristic of a polishing component indicative of material being removed from a planarized surface of the substrate, wherein the polishing component comprises byproducts produced by polishing the substrate and the characteristic is a measurable characteristic, and wherein monitoring a characteristic comprises sensing the measurable characteristic of the byproducts; and

stopping removal of material from the substrate when the characteristic of the polishing component is at a predetermined value that indicates the material being removed from the planarized surface is at the desired endpoint of the substrate.

15. (Twice Amended) A method for stopping polishing of a substrate at a desired endpoint, comprising:

monitoring a characteristic of a polishing component indicative of material being removed from a planarized surface of the substrate, wherein the polishing component comprises byproducts produced by polishing the substrate and the characteristic is a determinable characteristic and wherein monitoring a characteristic comprises determining the determinable characteristic of the byproducts; and

stopping removal of material from the substrate when the characteristic of the polishing component is at a predetermined value that indicates the material being removed from the planarized surface is at the desired endpoint of the substrate.